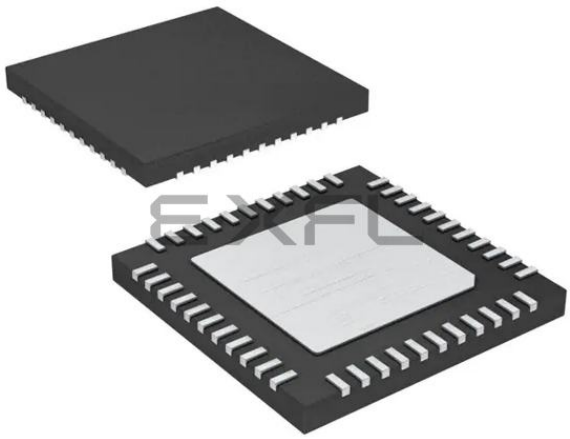


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	64KB (32K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	3.8K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf4620-i-ml

Table of Contents

TABLE 1-1: DEVICE FEATURES

Features	PIC18F2525	PIC18F2620	PIC18F4525	PIC18F4620
Operating Frequency	DC – 40 MHz	DC – 40 MHz	DC – 40 MHz	DC – 40 MHz
Program Memory (Bytes)	49152	65536	49152	65536
Program Memory (Instructions)	24576	32768	24576	32768
Data Memory (Bytes)	3968	3968	3968	3968
Data EEPROM Memory (Bytes)	1024	1024	1024	1024
Interrupt Sources	19	19	20	20
I/O Ports	Ports A, B, C, (E)	Ports A, B, C, (E)	Ports A, B, C, D, E	Ports A, B, C, D, E
Timers	4	4	4	4
Capture/Compare/PWM Modules	2	2	1	1
Enhanced Capture/Compare/ PWM Modules	0	0	1	1
Serial Communications	MSSP, Enhanced USART	MSSP, Enhanced USART	MSSP, Enhanced USART	MSSP, Enhanced USART
Parallel Communications (PSP)	No	No	Yes	Yes
10-Bit Analog-to-Digital Module	10 Input Channels	10 Input Channels	13 Input Channels	13 Input Channels
Resets (and Delays)	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), $\overline{\text{MCLR}}$ (optional), WDT	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), $\overline{\text{MCLR}}$ (optional), WDT	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), $\overline{\text{MCLR}}$ (optional), WDT	POR, BOR, RESET Instruction, Stack Full, Stack Underflow (PWRT, OST), $\overline{\text{MCLR}}$ (optional), WDT
Programmable Low-Voltage Detect	Yes	Yes	Yes	Yes
Programmable Brown-out Reset	Yes	Yes	Yes	Yes
Instruction Set	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled
Packages	28-Pin SPDIP 28-Pin SOIC	28-Pin SPDIP 28-Pin SOIC	40-Pin PDIP 44-Pin QFN 44-Pin TQFP	40-Pin PDIP 44-Pin QFN 44-Pin TQFP

TABLE 1-3: PIC18F4525/4620 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	QFN	TQFP			
						PORTA is a bidirectional I/O port.
RA0/AN0	2	19	19			
RA0				I/O	TTL	Digital I/O.
AN0				I	Analog	Analog input 0.
RA1/AN1	3	20	20			
RA1				I/O	TTL	Digital I/O.
AN1				I	Analog	Analog input 1.
RA2/AN2/VREF-/CVREF	4	21	21			
RA2				I/O	TTL	Digital I/O.
AN2				I	Analog	Analog input 2.
VREF-				I	Analog	A/D reference voltage (low) input.
CVREF				O	Analog	Comparator reference voltage output.
RA3/AN3/VREF+	5	22	22			
RA3				I/O	TTL	Digital I/O.
AN3				I	Analog	Analog input 3.
VREF+				I	Analog	A/D reference voltage (high) input.
RA4/T0CKI/C1OUT	6	23	23			
RA4				I/O	ST	Digital I/O.
T0CKI				I	ST	Timer0 external clock input.
C1OUT				O	—	Comparator 1 output.
RA5/AN4/$\overline{SS}$/HLVDIN/C2OUT	7	24	24			
RA5				I/O	TTL	Digital I/O.
AN4				I	Analog	Analog input 4.
$\overline{SS}$				I	TTL	SPI slave select input.
HLVDIN				I	Analog	High/Low-Voltage Detect input.
C2OUT				O	—	Comparator 2 output.
RA6						See the OSC2/CLKO/RA6 pin.
RA7						See the OSC1/CLKI/RA7 pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: Default assignment for CCP2 when the CCP2MX Configuration bit is set.

2: Alternate assignment for CCP2 when the CCP2MX Configuration bit is cleared.

3: For the QFN package, it is recommended that the bottom pad be connected to VSS.

REGISTER 2-1: OSCTUNE: OSCILLATOR TUNING REGISTER

R/W-0	R/W-0(1)	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTSRC	PLLEN(1)	—	TUN4	TUN3	TUN2	TUN1	TUN0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **INTSRC:** Internal Oscillator Low-Frequency Source Select bit
1 = 31.25 kHz device clock derived from 8 MHz INTOSC source (divide-by-256 enabled)
0 = 31 kHz device clock derived directly from INTRC internal oscillator

bit 6 **PLLEN:** Frequency Multiplier PLL for INTOSC Enable bit(1)
1 = PLL enabled for INTOSC (4 MHz and 8 MHz only)
0 = PLL disabled

bit 5 **Unimplemented:** Read as '0'

bit 4-0 **TUN4:TUN0:** Frequency Tuning bits
011111 = Maximum frequency
• •
• •
000001
000000 = Center frequency. Oscillator module is running at the calibrated frequency.
111111
• •
• •
100000 = Minimum frequency

Note 1: Available only in certain oscillator configurations; otherwise, this bit is unavailable and reads as '0'. See **Section 2.6.4 "PLL in INTOSC Modes"** for details.

2.6.5.1 Compensating with the EUSART

An adjustment may be required when the EUSART begins to generate framing errors or receives data with errors while in Asynchronous mode. Framing errors indicate that the device clock frequency is too high; to adjust for this, decrement the value in OSCTUNE to reduce the clock frequency. On the other hand, errors in data may suggest that the clock speed is too low; to compensate, increment OSCTUNE to increase the clock frequency.

2.6.5.2 Compensating with the Timers

This technique compares device clock speed to some reference clock. Two timers may be used; one timer is clocked by the peripheral clock, while the other is clocked by a fixed reference source, such as the Timer1 oscillator.

Both timers are cleared, but the timer clocked by the reference generates interrupts. When an interrupt occurs, the internally clocked timer is read and both timers are cleared. If the internally clocked timer value is greater than expected, then the internal oscillator block is running too fast. To adjust for this, decrement the OSCTUNE register.

2.6.5.3 Compensating with the CCP Module in Capture Mode

A CCP module can use free-running Timer1 (or Timer3), clocked by the internal oscillator block and an external event with a known period (i.e., AC power frequency). The time of the first event is captured in the CCPRxH:CCPRxL registers and is recorded for use later. When the second event causes a capture, the time of the first event is subtracted from the time of the second event. Since the period of the external event is known, the time difference between events can be calculated.

If the measured time is much greater than the calculated time, the internal oscillator block is running too fast; to compensate, decrement the OSCTUNE register. If the measured time is much less than the calculated time, the internal oscillator block is running too slow; to compensate, increment the OSCTUNE register.

4.6 Reset State of Registers

Most registers are unaffected by a Reset. Their status is unknown on POR and unchanged by all other Resets. The other registers are forced to a “Reset state” depending on the type of Reset that occurred.

Most registers are not affected by a WDT wake-up, since this is viewed as the resumption of normal operation. Status bits from the RCON register, $\overline{RI}$, $\overline{TO}$, $\overline{PD}$, $\overline{POR}$ and $\overline{BOR}$, are set or cleared differently in different Reset situations, as indicated in Table 4-3. These bits are used in software to determine the nature of the Reset.

Table 4-4 describes the Reset states for all of the Special Function Registers. These are categorized by Power-on and Brown-out Resets, Master Clear and WDT Resets and WDT wake-ups.

TABLE 4-3: STATUS BITS, THEIR SIGNIFICANCE AND THE INITIALIZATION CONDITION FOR RCON REGISTER

Condition	Program Counter	RCON Register						STKPTR Register	
		SBOREN	$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$	STKFUL	STKUNF
Power-on Reset	0000h	1	1	1	1	0	0	0	0
RESET Instruction	0000h	u(2)	0	u	u	u	u	u	u
Brown-out Reset	0000h	u(2)	1	1	1	u	0	u	u
$\overline{MCLR}$ during power-managed Run Modes	0000h	u(2)	u	1	u	u	u	u	u
$\overline{MCLR}$ during power-managed Idle modes and Sleep mode	0000h	u(2)	u	1	0	u	u	u	u
WDT time-out during full power or power-managed Run mode	0000h	u(2)	u	0	u	u	u	u	u
$\overline{MCLR}$ during full-power execution	0000h	u(2)	u	u	u	u	u	u	u
Stack Full Reset (STVREN = 1)	0000h	u(2)	u	u	u	u	u	1	u
Stack Underflow Reset (STVREN = 1)	0000h	u(2)	u	u	u	u	u	u	1
Stack Underflow Error (not an actual Reset, STVREN = 0)	0000h	u(2)	u	u	u	u	u	u	1
WDT time-out during power-managed Idle or Sleep modes	PC + 2	u(2)	u	0	0	u	u	u	u
Interrupt exit from power-managed modes	PC + 2(1)	u(2)	u	u	0	u	u	u	u

Legend: u = unchanged

Note 1: When the wake-up is due to an interrupt and the GIEH or GIEL bits are set, the PC is loaded with the interrupt vector (008h or 0018h).

2: Reset state is ‘1’ for POR and unchanged for all other Resets when software BOR is enabled (BOREN1:BOREN0 Configuration bits = 01 and SBOREN = 1); otherwise, the Reset state is ‘0’.

TABLE 5-2: REGISTER FILE SUMMARY (PIC18F2525/2620/4525/4620)

File Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Details on page:
TOSU	—	—	—	Top-of-Stack Upper Byte (TOS<20:16>)					---0 0000	49, 54
TOSH	Top-of-Stack High Byte (TOS<15:8>)								0000 0000	49, 54
TOSL	Top-of-Stack Low Byte (TOS<7:0>)								0000 0000	49, 54
STKPTR	STKFUL(6)	STKUNF(6)	—	SP4	SP3	SP2	SP1	SP0	00-0 0000	49, 55
PCLATU	—	—	—	Holding Register for PC<20:16>					---0 0000	49, 54
PCLATH	Holding Register for PC<15:8>								0000 0000	49, 54
PCL	PC Low Byte (PC<7:0>)								0000 0000	49, 54
TBLPTRU	—	—	bit 21	Program Memory Table Pointer Upper Byte (TBLPTR<20:16>)					--00 0000	49, 82
TBLPTRH	Program Memory Table Pointer High Byte (TBLPTR<15:8>)								0000 0000	49, 82
TBLPTRL	Program Memory Table Pointer Low Byte (TBLPTR<7:0>)								0000 0000	49, 82
TABLAT	Program Memory Table Latch								0000 0000	49, 82
PRODH	Product Register High Byte								xxxx xxxx	49, 89
PRODL	Product Register Low Byte								xxxx xxxx	49, 89
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	49, 111
INTCON2	$\overline{\text{RBPU}}$	INTEDG0	INTEDG1	INTEDG2	—	TMR0IP	—	RBIP	1111 -1-1	49, 112
INTCON3	INT2IP	INT1IP	—	INT2IE	INT1IE	—	INT2IF	INT1IF	11-0 0-00	49, 113
INDF0	Uses contents of FSR0 to address data memory – value of FSR0 not changed (not a physical register)								N/A	49, 68
POSTINC0	Uses contents of FSR0 to address data memory – value of FSR0 post-incremented (not a physical register)								N/A	49, 68
POSTDEC0	Uses contents of FSR0 to address data memory – value of FSR0 post-decremented (not a physical register)								N/A	49, 68
PREINC0	Uses contents of FSR0 to address data memory – value of FSR0 pre-incremented (not a physical register)								N/A	49, 68
PLUSW0	Uses contents of FSR0 to address data memory – value of FSR0 pre-incremented (not a physical register) – value of FSR0 offset by W								N/A	49, 68
FSR0H	—	—	—	—	Indirect Data Memory Address Pointer 0 High Byte				---- 0000	49, 68
FSR0L	Indirect Data Memory Address Pointer 0 Low Byte								xxxx xxxx	49, 68
WREG	Working Register								xxxx xxxx	49
INDF1	Uses contents of FSR1 to address data memory – value of FSR1 not changed (not a physical register)								N/A	49, 68
POSTINC1	Uses contents of FSR1 to address data memory – value of FSR1 post-incremented (not a physical register)								N/A	49, 68
POSTDEC1	Uses contents of FSR1 to address data memory – value of FSR1 post-decremented (not a physical register)								N/A	49, 68
PREINC1	Uses contents of FSR1 to address data memory – value of FSR1 pre-incremented (not a physical register)								N/A	49, 68
PLUSW1	Uses contents of FSR1 to address data memory – value of FSR1 pre-incremented (not a physical register) – value of FSR1 offset by W								N/A	49, 68
FSR1H	—	—	—	—	Indirect Data Memory Address Pointer 1 High Byte				---- 0000	50, 68
FSR1L	Indirect Data Memory Address Pointer 1 Low Byte								xxxx xxxx	50, 68
BSR	—	—	—	—	Bank Select Register				---- 0000	50, 59
INDF2	Uses contents of FSR2 to address data memory – value of FSR2 not changed (not a physical register)								N/A	50, 68
POSTINC2	Uses contents of FSR2 to address data memory – value of FSR2 post-incremented (not a physical register)								N/A	50, 68
POSTDEC2	Uses contents of FSR2 to address data memory – value of FSR2 post-decremented (not a physical register)								N/A	50, 68
PREINC2	Uses contents of FSR2 to address data memory – value of FSR2 pre-incremented (not a physical register)								N/A	50, 68
PLUSW2	Uses contents of FSR2 to address data memory – value of FSR2 pre-incremented (not a physical register) – value of FSR2 offset by W								N/A	50, 68
FSR2H	—	—	—	—	Indirect Data Memory Address Pointer 2 High Byte				---- 0000	50, 68
FSR2L	Indirect Data Memory Address Pointer 2 Low Byte								xxxx xxxx	50, 68
STATUS	—	—	—	N	OV	Z	DC	C	---x xxxx	50, 66

Legend: x = unknown, u = unchanged, – = unimplemented, q = value depends on condition

Note 1: The SBOREN bit is only available when the BOREN1:BOREN0 Configuration bits = 01; otherwise, it is disabled and reads as '0'. See **Section 4.4 "Brown-out Reset (BOR)"**.

2: These registers and/or bits are not implemented on 28-pin devices and are read as '0'. Reset values are shown for 40/44-pin devices; individual unimplemented bits should be interpreted as '-'.

3: The PLLEN bit is only available in specific oscillator configurations; otherwise, it is disabled and reads as '0'. See **Section 2.6.4 "PLL in INTOSC Modes"**.

4: The RE3 bit is only available when Master Clear Reset is disabled (MCLRE Configuration bit = 0); otherwise, RE3 reads as '0'. This bit is read-only.

5: RA6/RA7 and their associated latch and direction bits are individually configured as port pins based on various primary oscillator modes. When disabled, these bits read as '0'.

6: Bit 7 and bit 6 are cleared by user software or by a POR.

10.2 PIR Registers

The PIR registers contain the individual flag bits for the peripheral interrupts. Due to the number of peripheral interrupt sources, there are two Peripheral Interrupt Request (Flag) registers (PIR1 and PIR2).

Note 1: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Interrupt Enable bit, GIE (INTCON<7>).

2: User software should ensure the appropriate interrupt flag bits are cleared prior to enabling an interrupt and after servicing that interrupt.

REGISTER 10-4: PIR1: PERIPHERAL INTERRUPT REQUEST (FLAG) REGISTER 1

R/W-0	R/W-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **PSPIF:** Parallel Slave Port Read/Write Interrupt Flag bit(1)
1 = A read or a write operation has taken place (must be cleared in software)
0 = No read or write has occurred

bit 6 **ADIF:** A/D Converter Interrupt Flag bit
1 = An A/D conversion completed (must be cleared in software)
0 = The A/D conversion is not complete

bit 5 **RCIF:** EUSART Receive Interrupt Flag bit
1 = The EUSART receive buffer, RCREG, is full (cleared when RCREG is read)
0 = The EUSART receive buffer is empty

bit 4 **TXIF:** EUSART Transmit Interrupt Flag bit
1 = The EUSART transmit buffer, TXREG, is empty (cleared when TXREG is written)
0 = The EUSART transmit buffer is full

bit 3 **SSPIF:** Master Synchronous Serial Port Interrupt Flag bit
1 = The transmission/reception is complete (must be cleared in software)
0 = Waiting to transmit/receive

bit 2 **CCP1IF:** CCP1 Interrupt Flag bit
Capture mode:
1 = A TMR1 register capture occurred (must be cleared in software)
0 = No TMR1 register capture occurred
Compare mode:
1 = A TMR1 register compare match occurred (must be cleared in software)
0 = No TMR1 register compare match occurred
PWM mode:
Unused in this mode.

bit 1 **TMR2IF:** TMR2 to PR2 Match Interrupt Flag bit
1 = TMR2 to PR2 match occurred (must be cleared in software)
0 = No TMR2 to PR2 match occurred

bit 0 **TMR1IF:** TMR1 Overflow Interrupt Flag bit
1 = TMR1 register overflowed (must be cleared in software)
0 = TMR1 register did not overflow

Note 1: This bit is unimplemented on 28-pin devices and will read as '0'.

15.2 Capture Mode

In Capture mode, the CCPRxH:CCPRxL register pair captures the 16-bit value of the TMR1 or TMR3 registers when an event occurs on the corresponding CCPx pin. An event is defined as one of the following:

- every falling edge
- every rising edge
- every 4th rising edge
- every 16th rising edge

The event is selected by the mode select bits, CCPxM3:CCPxM0 (CCPxCON<3:0>). When a capture is made, the interrupt request flag bit, CCPxIF, is set; it must be cleared in software. If another capture occurs before the value in register CCPRx is read, the old captured value is overwritten by the new captured value.

15.2.1 CCP PIN CONFIGURATION

In Capture mode, the appropriate CCPx pin should be configured as an input by setting the corresponding TRIS direction bit.

Note:	If RB3/CCP2 or RC1/CCP2 is configured as an output, a write to the port can cause a capture condition.

15.2.2 TIMER1/TIMER3 MODE SELECTION

The timers that are to be used with the capture feature (Timer1 and/or Timer3) must be running in Timer mode or Synchronized Counter mode. In Asynchronous Counter mode, the capture operation will not work. The timer to be used with each CCP module is selected in the T3CON register (see **Section 15.1.1 "CCP Modules and Timer Resources"**).

15.2.3 SOFTWARE INTERRUPT

When the Capture mode is changed, a false capture interrupt may be generated. The user should keep the CCPxIE interrupt enable bit clear to avoid false interrupts. The interrupt flag bit, CCPxIF, should also be cleared following any such change in operating mode.

15.2.4 CCP PRESCALER

There are four prescaler settings in Capture mode; they are specified as part of the operating mode selected by the mode select bits (CCPxM3:CCPxM0). Whenever the CCP module is turned off or Capture mode is disabled, the prescaler counter is cleared. This means that any Reset will clear the prescaler counter.

Switching from one capture prescaler to another may generate an interrupt. Also, the prescaler counter will not be cleared; therefore, the first capture may be from a non-zero prescaler. Example 15-1 shows the recommended method for switching between capture prescalers. This example also clears the prescaler counter and will not generate the "false" interrupt.

EXAMPLE 15-1: CHANGING BETWEEN CAPTURE PRESCALERS (CCP2 SHOWN)

```
CLRF   CCP2CON      ; Turn CCP module off
MOVLW  NEW_CAPT_PS  ; Load WREG with the
                    ; new prescaler mode
                    ; value and CCP ON
MOVWF  CCP2CON      ; Load CCP2CON with
                    ; this value
```

FIGURE 15-1: CAPTURE MODE OPERATION BLOCK DIAGRAM

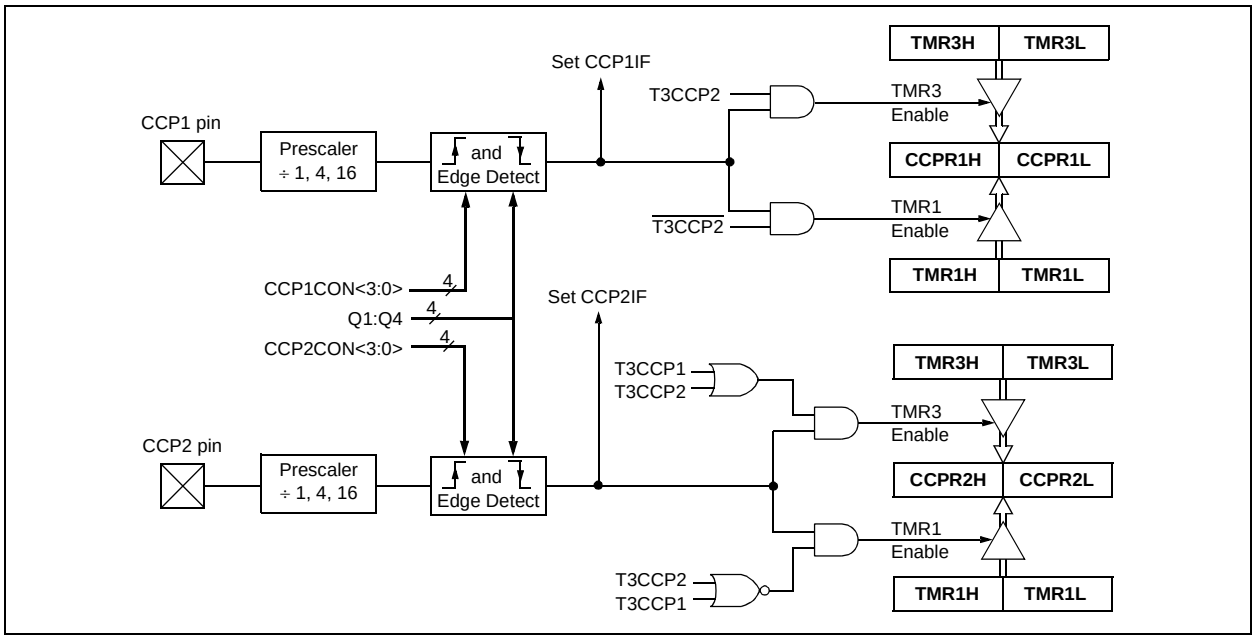
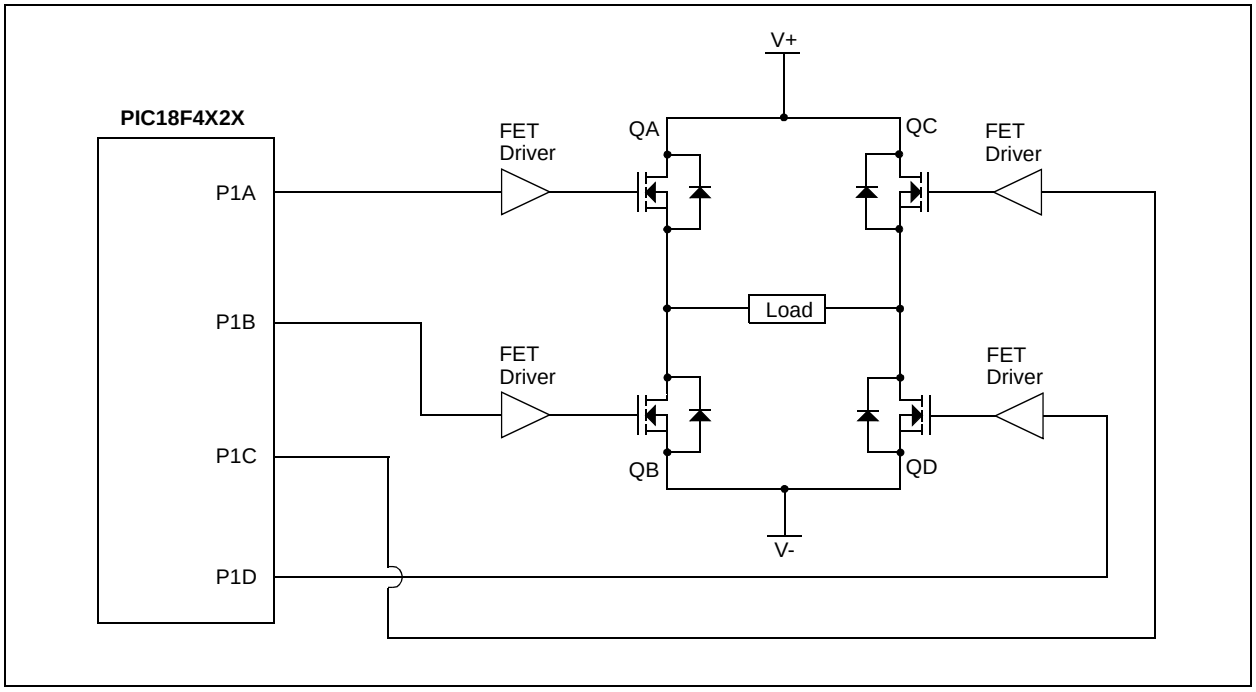


FIGURE 16-7: EXAMPLE OF FULL-BRIDGE APPLICATION



16.4.5.1 Direction Change in Full-Bridge Mode

In the Full-Bridge Output mode, the P1M1 bit in the CCP1CON register allows user to control the forward/ reverse direction. When the application firmware changes this direction control bit, the module will assume the new direction on the next PWM cycle.

Just before the end of the current PWM period, the modulated outputs (P1B and P1D) are placed in their inactive state, while the unmodulated outputs (P1A and P1C) are switched to drive in the opposite direction. This occurs in a time interval of 4 TOSC * (Timer2 Prescale Value) before the next PWM period begins. The Timer2 prescaler will be either 1, 4 or 16, depending on the value of the T2CKPS1:T2CKPS0 bits (T2CON<1:0>). During the interval from the switch of the unmodulated outputs to the beginning of the next period, the modulated outputs (P1B and P1D) remain inactive. This relationship is shown in Figure 16-8.

Note that in the Full-Bridge Output mode, the CCP1 module does not provide any dead-band delay. In general, since only one output is modulated at all times, dead-band delay is not required. However, there is a situation where a dead-band delay might be required. This situation occurs when both of the following conditions are true:

1. The direction of the PWM output changes when the duty cycle of the output is at or near 100%.
2. The turn-off time of the power switch, including the power device and driver circuit, is greater than the turn-on time.

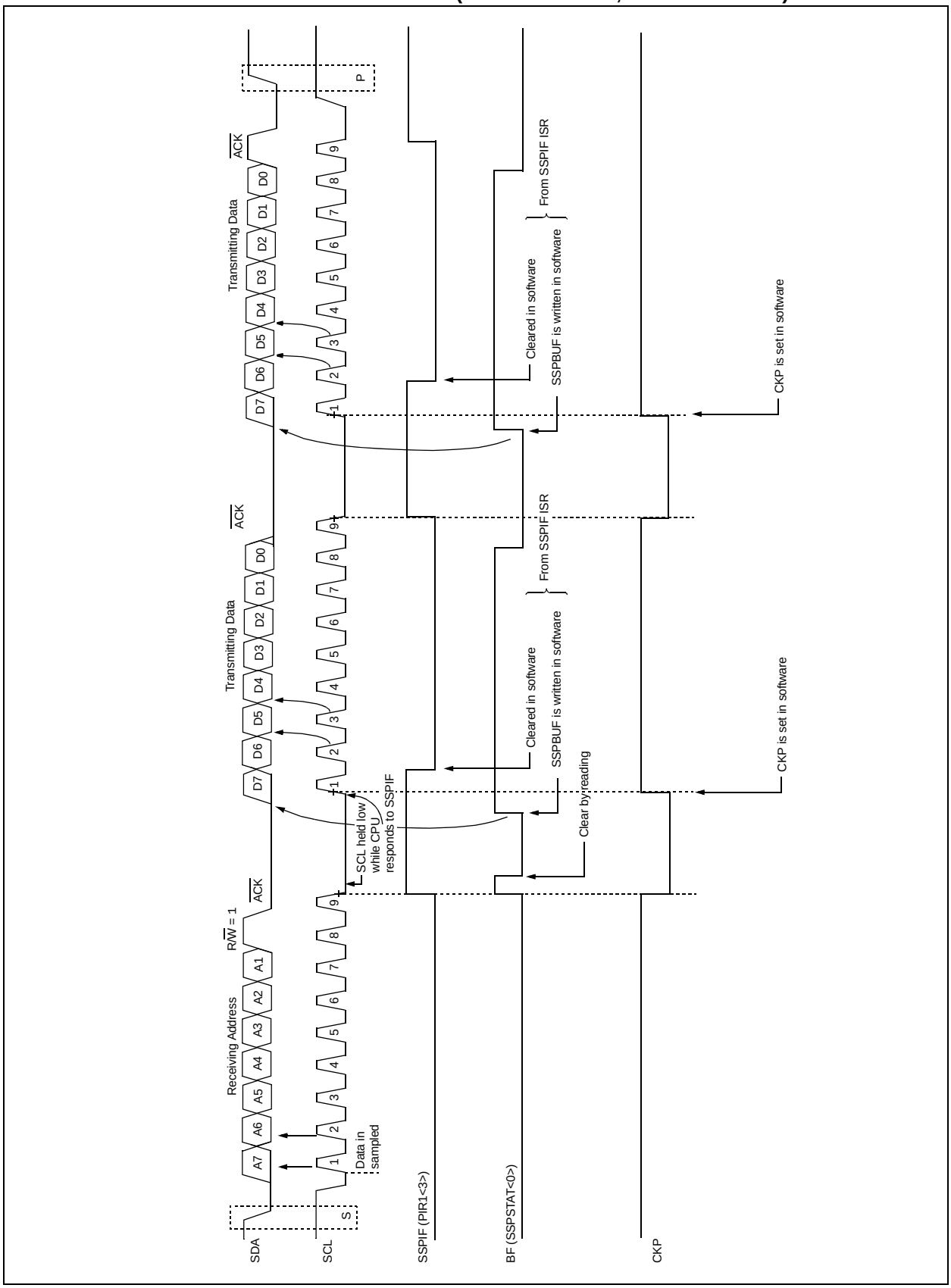
Figure 16-9 shows an example where the PWM direction changes from forward to reverse at a near 100% duty cycle. At time t1, the outputs P1A and P1D become inactive, while output P1C becomes active. In this example, since the turn-off time of the power devices is longer than the turn-on time, a shoot-through current may flow through power devices, QC and QD (see Figure 16-7), for the duration of ‘t’. The same phenomenon will occur to power devices, QA and QB, for PWM direction change from reverse to forward.

If changing PWM direction at high duty cycle is required for an application, one of the following requirements must be met:

1. Reduce PWM for a PWM period before changing directions.
2. Use switch drivers that can drive the switches off faster than they can drive them on.

Other options to prevent shoot-through current may exist.

FIGURE 17-9: I²C™ SLAVE MODE TIMING (TRANSMISSION, 7-BIT ADDRESS)



22.1 Operation

When the HLVD module is enabled, a comparator uses an internally generated reference voltage as the set point. The set point is compared with the trip point, where each node in the resistor divider represents a trip point voltage. The “trip point” voltage is the voltage level at which the device detects a high or low-voltage event, depending on the configuration of the module. When the supply voltage is equal to the trip point, the voltage tapped off of the resistor array is equal to the internal reference voltage generated by the voltage reference module. The comparator then generates an interrupt signal by setting the HLVDIF bit.

The trip point voltage is software programmable to any one of 16 values. The trip point is selected by programming the HLVDL3:HLVDL0 bits (HLVDCON<3:0>).

The HLVD module has an additional feature that allows the user to supply the trip voltage to the module from an external source. This mode is enabled when bits HLVDL3:HLVDL0 are set to ‘1111’. In this state, the comparator input is multiplexed from the external input pin, HLVDIN. This gives users flexibility because it allows them to configure the High/Low-Voltage Detect interrupt to occur at any voltage in the valid operating range.

FIGURE 22-1: HLVD MODULE BLOCK DIAGRAM (WITH EXTERNAL INPUT)

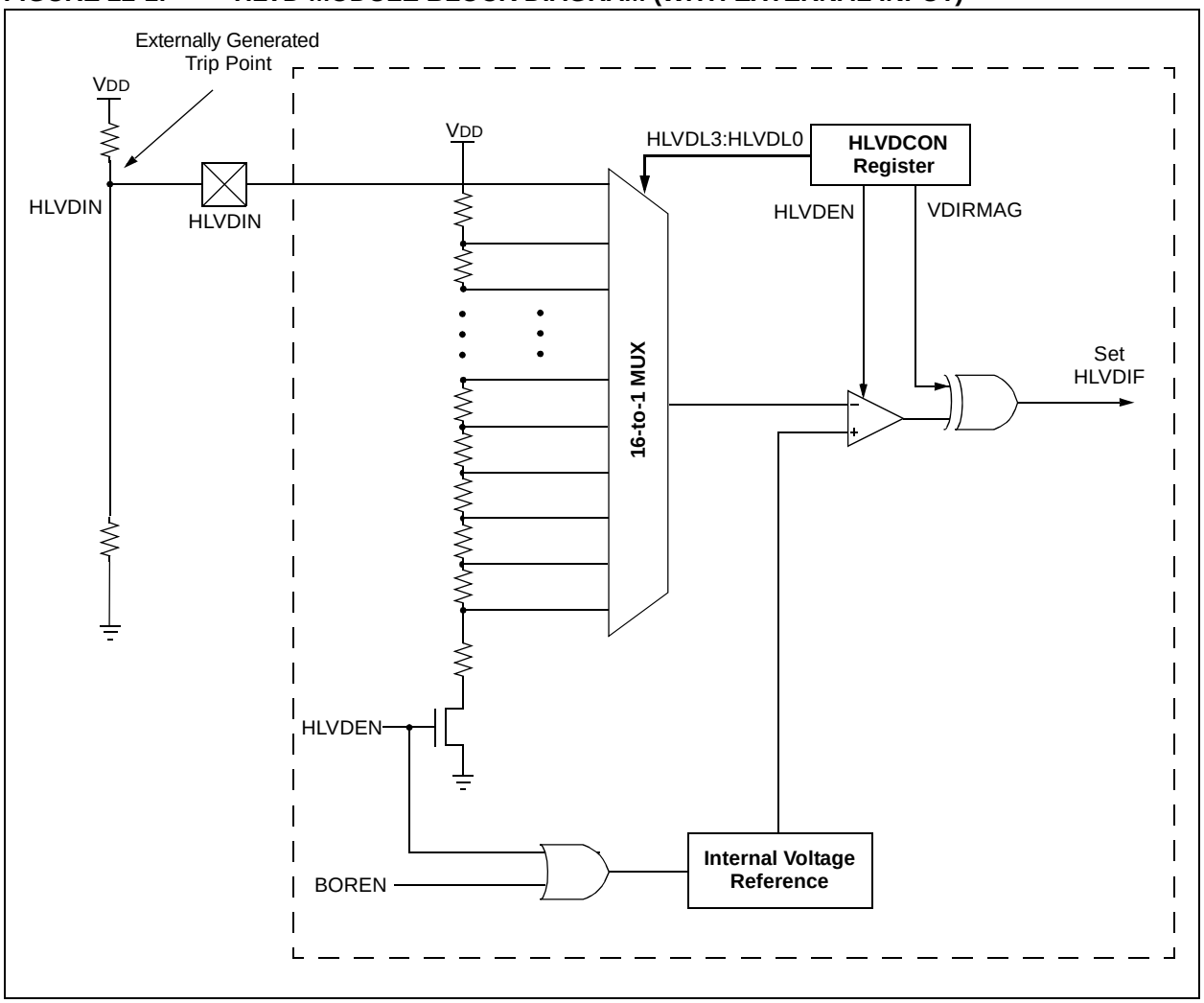
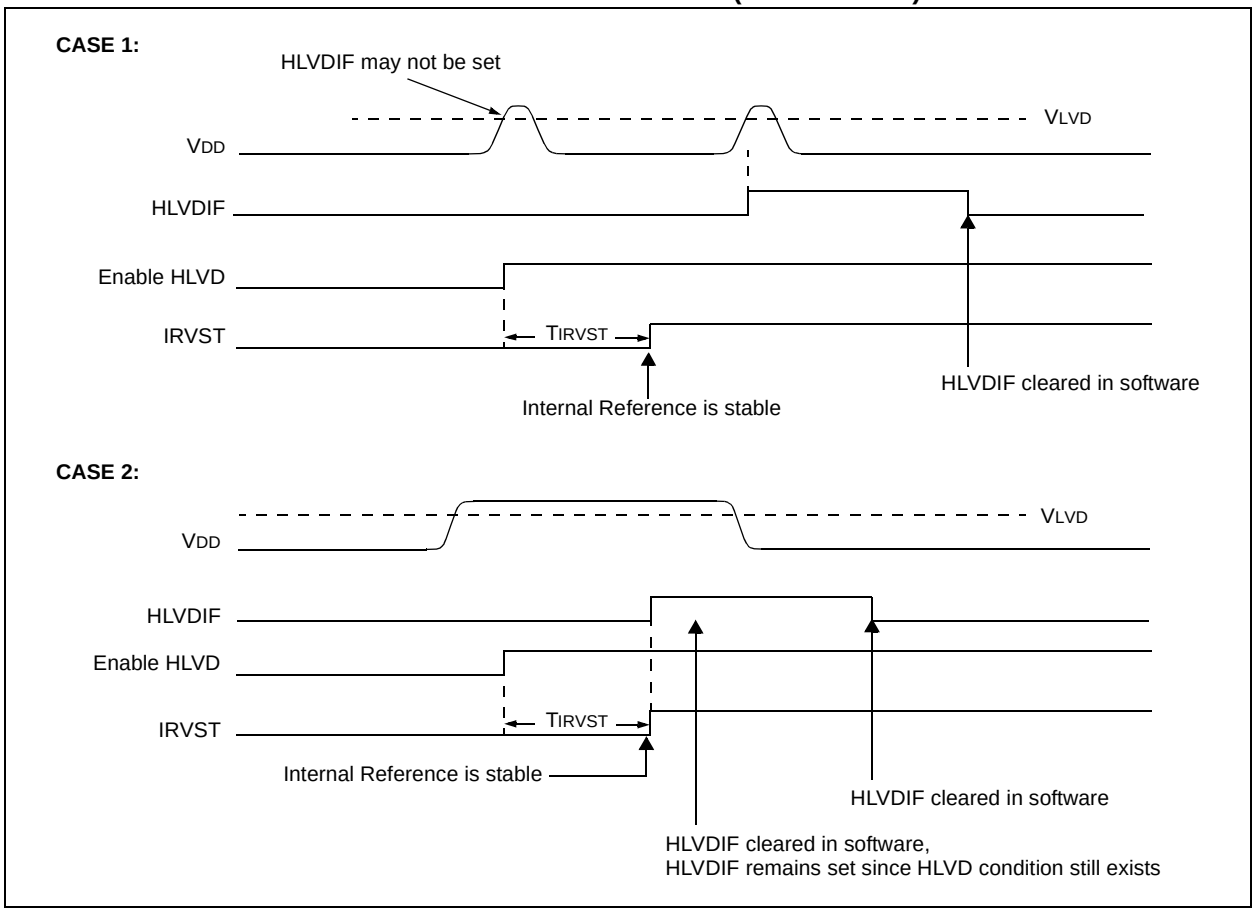


FIGURE 22-3: HIGH-VOLTAGE DETECT OPERATION (VDIRMAG = 1)

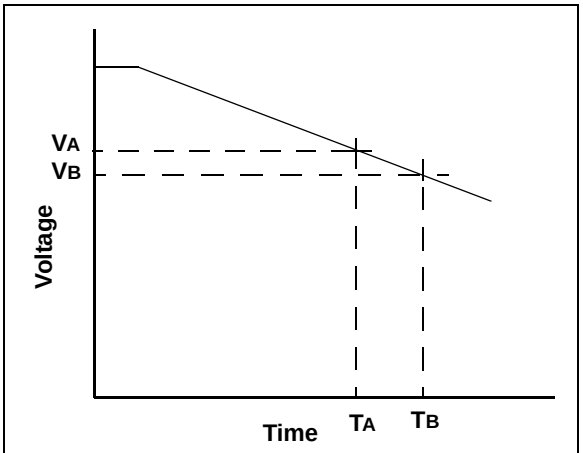


22.5 Applications

In many applications, the ability to detect a drop below or rise above a particular threshold is desirable. For example, the HLVD module could be periodically enabled to detect a Universal Serial Bus (USB) attach or detach. This assumes the device is powered by a lower voltage source than the USB when detached. An attach would indicate a high-voltage detect from, for example, 3.3V to 5V (the voltage on USB) and vice versa for a detach. This feature could save a design a few extra components and an attach signal (input pin).

For general battery applications, Figure 22-4 shows a possible voltage curve. Over time, the device voltage decreases. When the device voltage reaches voltage VA, the HLVD logic generates an interrupt at time TA. The interrupt could cause the execution of an ISR, which would allow the application to perform "house-keeping tasks" and perform a controlled shutdown before the device voltage exits the valid operating range at TB. The HLVD, thus, would give the application a time window, represented by the difference between TA and TB, to safely exit.

FIGURE 22-4: TYPICAL LOW-VOLTAGE DETECT APPLICATION



Legend: VA = HLVD trip point
VB = Minimum valid device operating voltage

POP **Pop Top of Return Stack**

Syntax: POP

Operands: None

Operation: (TOS) → bit bucket

Status Affected: None

Encoding:

0000	0000	0000	0110

Description: The TOS value is pulled off the return stack and is discarded. The TOS value then becomes the previous value that was pushed onto the return stack. This instruction is provided to enable the user to properly manage the return stack to incorporate a software stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	POP TOS value	No operation

Example:
```
POP
GOTO    NEW
```
Before Instruction
TOS = 0031A2h
Stack (1 level down) = 014332h

After Instruction
TOS = 014332h
PC = NEW

PUSH **Push Top of Return Stack**

Syntax: PUSH

Operands: None

Operation: (PC + 2) → TOS

Status Affected: None

Encoding:

0000	0000	0000	0101

Description: The PC + 2 is pushed onto the top of the return stack. The previous TOS value is pushed down on the stack. This instruction allows implementing a software stack by modifying TOS and then pushing it onto the return stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	PUSH PC + 2 onto return stack	No operation	No operation

Example:
```
PUSH
```
Before Instruction
TOS = 345Ah
PC = 0124h

After Instruction
PC = 0126h
TOS = 0126h
Stack (1 level down) = 345Ah

TBLWT **Table Write**

Syntax: TBLWT (*; *+; *-; +*)

Operands: None

Operation: if TBLWT*,
(TABLAT) → Holding Register,
TBLPTR – No Change;
if TBLWT*+,
(TABLAT) → Holding Register,
(TBLPTR) + 1 → TBLPTR;
if TBLWT*-,
(TABLAT) → Holding Register,
(TBLPTR) – 1 → TBLPTR;
if TBLWT+*,
(TBLPTR) + 1 → TBLPTR,
(TABLAT) → Holding Register

Status Affected: None

Encoding:

0000	0000	0000	11nn nn=0 * =1 *+ =2 *- =3 +*

Description: This instruction uses the 3 LSBs of TBLPTR to determine which of the 8 holding registers the TABLAT is written to. The holding registers are used to program the contents of Program Memory (P.M.). (Refer to **Section 7.0 "Flash Program Memory"** for additional details on programming Flash memory.)
The TBLPTR (a 21-bit pointer) points to each byte in the program memory. TBLPTR has a 2-Mbyte address range.
The LSb of the TBLPTR selects which byte of the program memory location to access.

TBLPTR[0] = 0: Least Significant Byte of Program Memory Word
TBLPTR[0] = 1: Most Significant Byte of Program Memory Word

The TBLWT instruction can modify the value of TBLPTR as follows:

- no change
- post-increment
- post-decrement
- pre-increment

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	No operation	No operation
No operation	No operation (Read TABLAT)	No operation	No operation (Write to Holding Register)

TBLWT **Table Write (Continued)**

Example 1: TBLWT *+;

Before Instruction
TABLAT = 55h
TBLPTR = 00A356h
HOLDING REGISTER (00A356h) = FFh
After Instructions (table write completion)
TABLAT = 55h
TBLPTR = 00A357h
HOLDING REGISTER (00A356h) = 55h

Example 2: TBLWT +*;

Before Instruction
TABLAT = 34h
TBLPTR = 01389Ah
HOLDING REGISTER (01389Ah) = FFh
HOLDING REGISTER (01389Bh) = FFh
After Instruction (table write completion)
TABLAT = 34h
TBLPTR = 01389Bh
HOLDING REGISTER (01389Ah) = FFh
HOLDING REGISTER (01389Bh) = 34h

ADDWF **ADD W to Indexed (Indexed Literal Offset mode)**

Syntax: ADDWF [k] {,d}

Operands: $0 \le k \le 95$
$d \in [0,1]$

Operation: (W) + ((FSR2) + k) → dest

Status Affected: N, OV, C, DC, Z

Encoding:

0010	01d0	kkkk	kkkk

Description: The contents of W are added to the contents of the register indicated by FSR2, offset by the value 'k'.
If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f' (default).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read 'k'	Process Data	Write to destination

Example: ADDWF [OFST], 0

Before Instruction
W = 17h
OFST = 2Ch
FSR2 = 0A00h
Contents of 0A2Ch = 20h
After Instruction
W = 37h
Contents of 0A2Ch = 20h

BSF **Bit Set Indexed (Indexed Literal Offset mode)**

Syntax: BSF [k], b

Operands: $0 \le f \le 95$
$0 \le b \le 7$

Operation: 1 → ((FSR2) + k)<b>

Status Affected: None

Encoding:

1000	bbb0	kkkk	kkkk

Description: Bit 'b' of the register indicated by FSR2, offset by the value 'k', is set.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: BSF [FLAG_OFST], 7

Before Instruction
FLAG_OFST = 0Ah
FSR2 = 0A00h
Contents of 0A0Ah = 55h
After Instruction
Contents of 0A0Ah = D5h

SETF **Set Indexed (Indexed Literal Offset mode)**

Syntax: SETF [k]

Operands: $0 \le k \le 95$

Operation: FFh → ((FSR2) + k)

Status Affected: None

Encoding:

0110	1000	kkkk	kkkk

Description: The contents of the register indicated by FSR2, offset by 'k', are set to FFh.

Words: 1

Cycles: 1

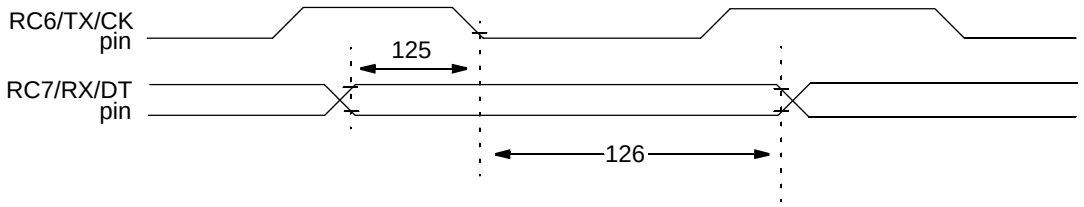
Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read 'k'	Process Data	Write register

Example: SETF [OFST]

Before Instruction
OFST = 2Ch
FSR2 = 0A00h
Contents of 0A2Ch = 00h
After Instruction
Contents of 0A2Ch = FFh

FIGURE 26-22: EUSART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



Note: Refer to Figure 26-5 for load conditions.

TABLE 26-23: EUSART SYNCHRONOUS RECEIVE REQUIREMENTS

Param. No.	Symbol	Characteristic	Min	Max	Units	Conditions
125	TdtV2ckl	SYNC RCV (MASTER & SLAVE) Data Hold before CK ↓ (DT hold time)	10	—	ns	
126	TckL2dtl	Data Hold after CK ↓ (DT hold time)	15	—	ns	

TABLE 26-24: A/D CONVERTER CHARACTERISTICS: PIC18F2525/2620/4525/4620 (INDUSTRIAL) PIC18LF2525/2620/4525/4620 (INDUSTRIAL)

Param No.	Symbol	Characteristic		Min	Typ	Max	Units	Conditions
A01	NR	Resolution		—	—	10	bit	ΔVREF ≥ 3.0V
A03	EIL	Integral Linearity Error		—	—	<±1	LSb	ΔVREF ≥ 3.0V
A04	EDL	Differential Linearity Error		—	—	<±1	LSb	ΔVREF ≥ 3.0V
A06	EOFF	Offset Error		—	—	<±2.0	LSb	ΔVREF ≥ 3.0V
A07	EGN	Gain Error		—	—	<±1	LSb	ΔVREF ≥ 3.0V
A10	—	Monotonicity		Guaranteed(1)			—	VSS ≤ VAIN ≤ VREF
A20	ΔVREF	Reference Voltage Range (VREFH – VREFL)		1.8 3	— —	— —	V V	VDD < 3.0V VDD ≥ 3.0V
A21	VREFH	Reference Voltage High		VSS	—	VREFH	V	
A22	VREFL	Reference Voltage Low		VSS – 0.3V	—	VDD – 3.0V	V	
A25	VAIN	Analog Input Voltage		VREFL	—	VREFH	V	
A30	ZAIN	Recommended Impedance of Analog Voltage Source		—	—	2.5	kΩ	
A40	IAD	A/D Current from VDD	PIC18**F**XXXX	—	180	—	μA	Average current during conversion
			PIC18**LF**XX20	—	90	—	μA	
A50	IREF	VREF Input Current(2)		— —	— —	5 150	μA μA	During VAIN acquisition. During A/D conversion cycle.

Note 1: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

2: VREFH current is from RA3/AN3/VREF+ pin or VDD, whichever is selected as the VREFH source. VREFL current is from RA2/AN2/VREF-/CVREF pin or VSS, whichever is selected as the VREFL source.

27.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES

Note:	The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean – 3σ) respectively, where σ is a standard deviation, over the whole temperature range.

FIGURE 27-1: SLEEP MODE

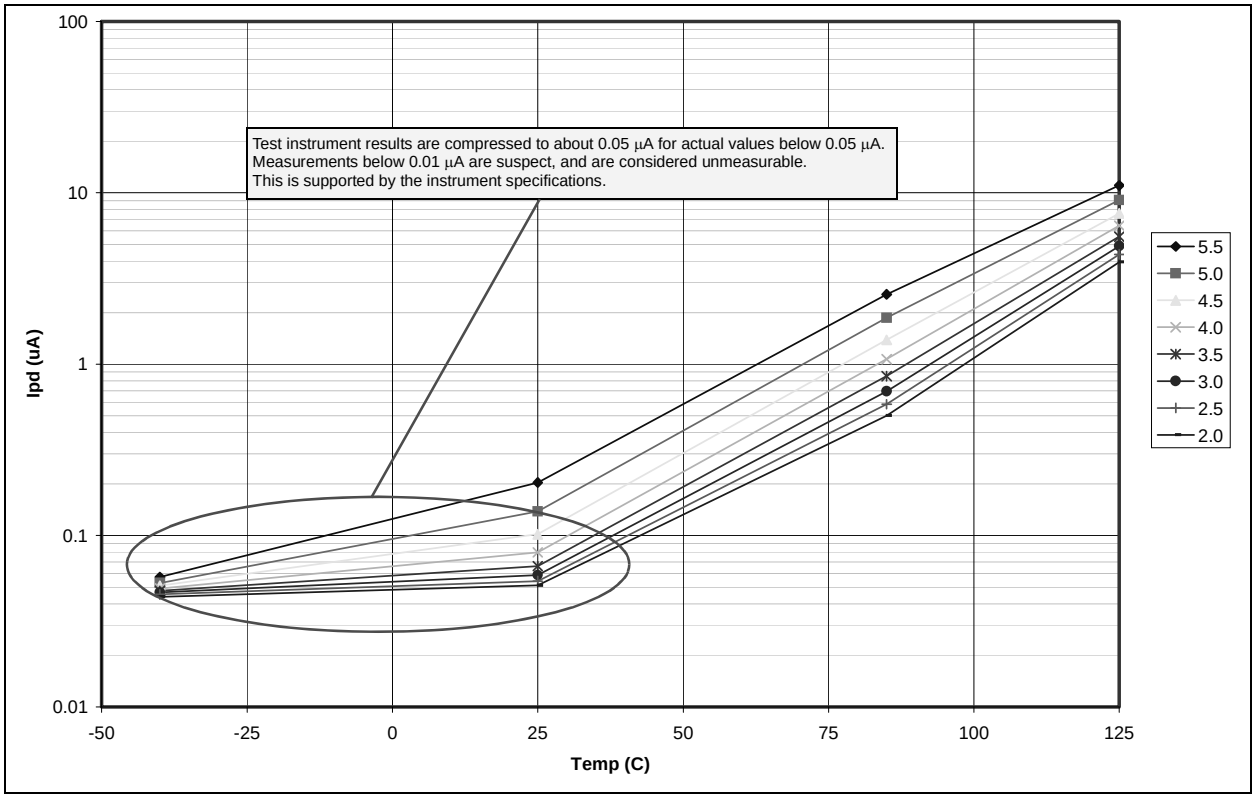


FIGURE 27-13: TYPICAL AND MAXIMUM IDD ACROSS VDD (RC_RUN MODE, 31 kHz)

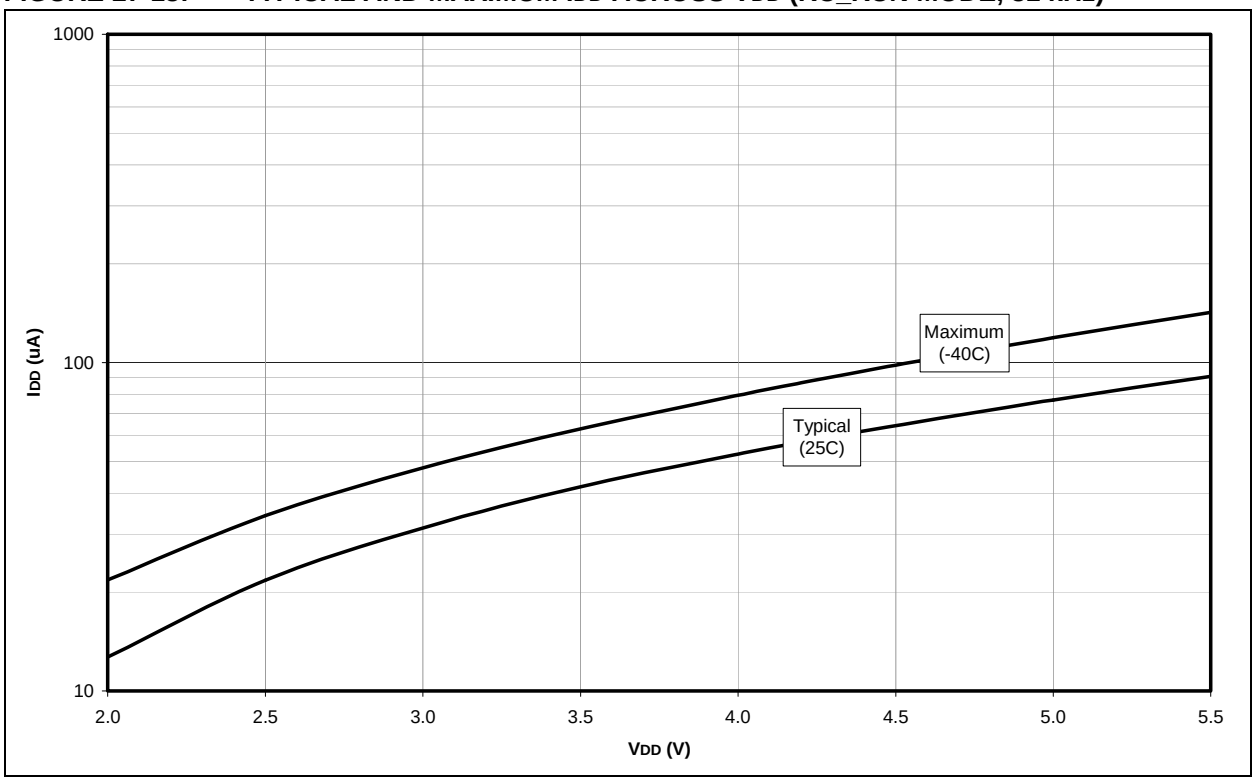


FIGURE 27-14: TYPICAL IDD ACROSS VDD (RC_IDLE MODE, 25°C)

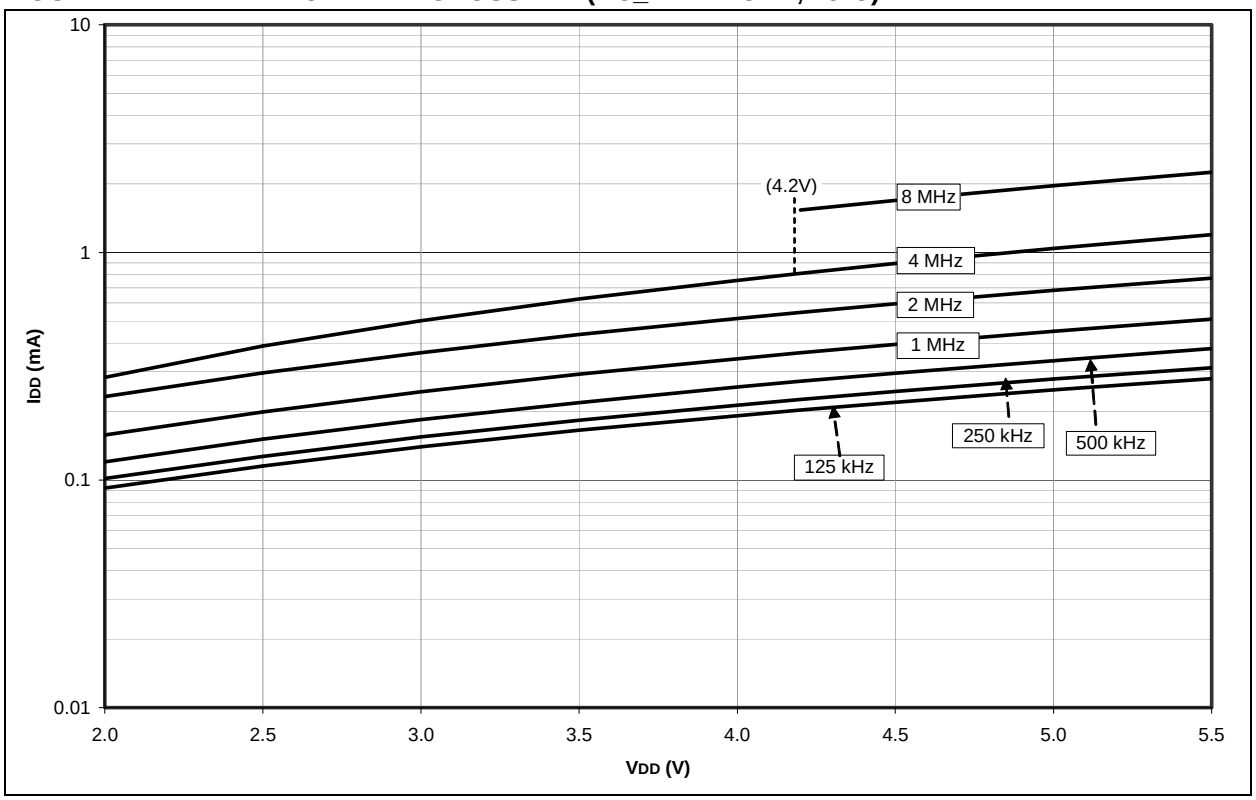


FIGURE 27-15: MAXIMUM IDD ACROSS VDD (RC_IDLE MODE, -40°C-85°C)

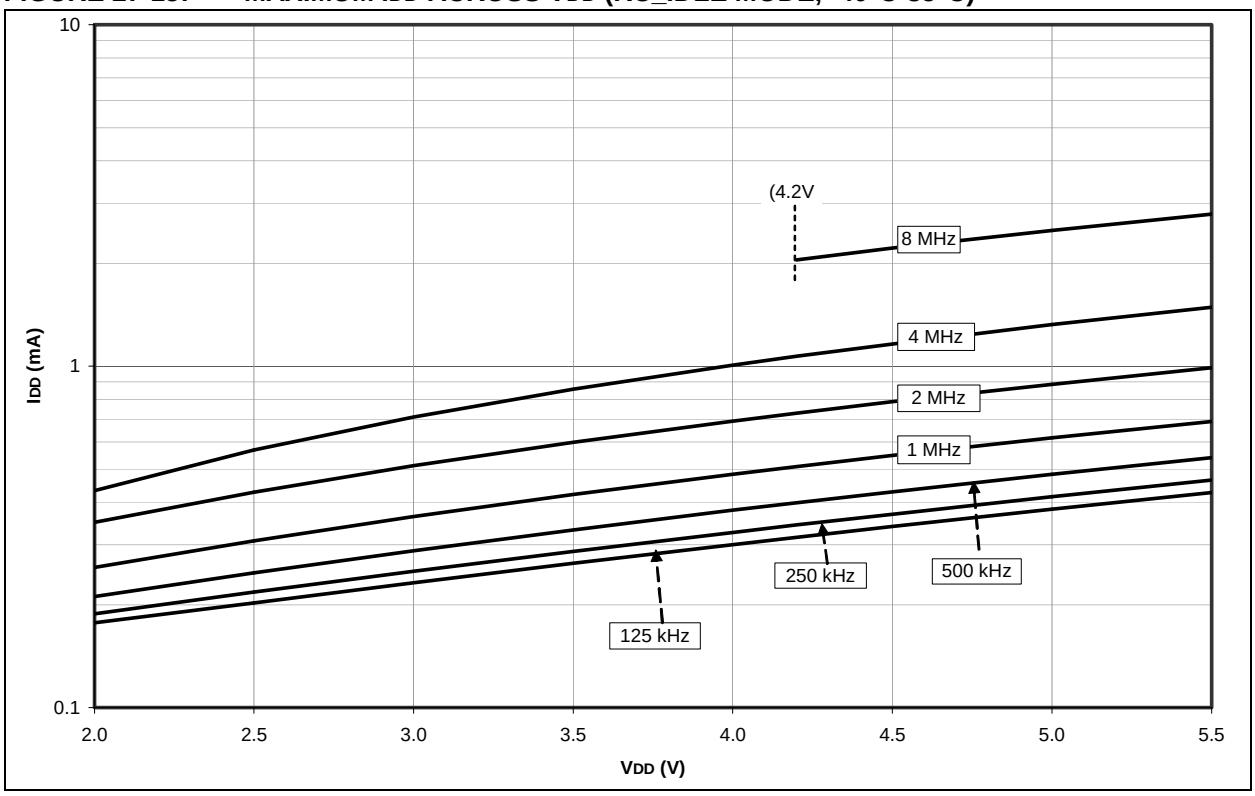
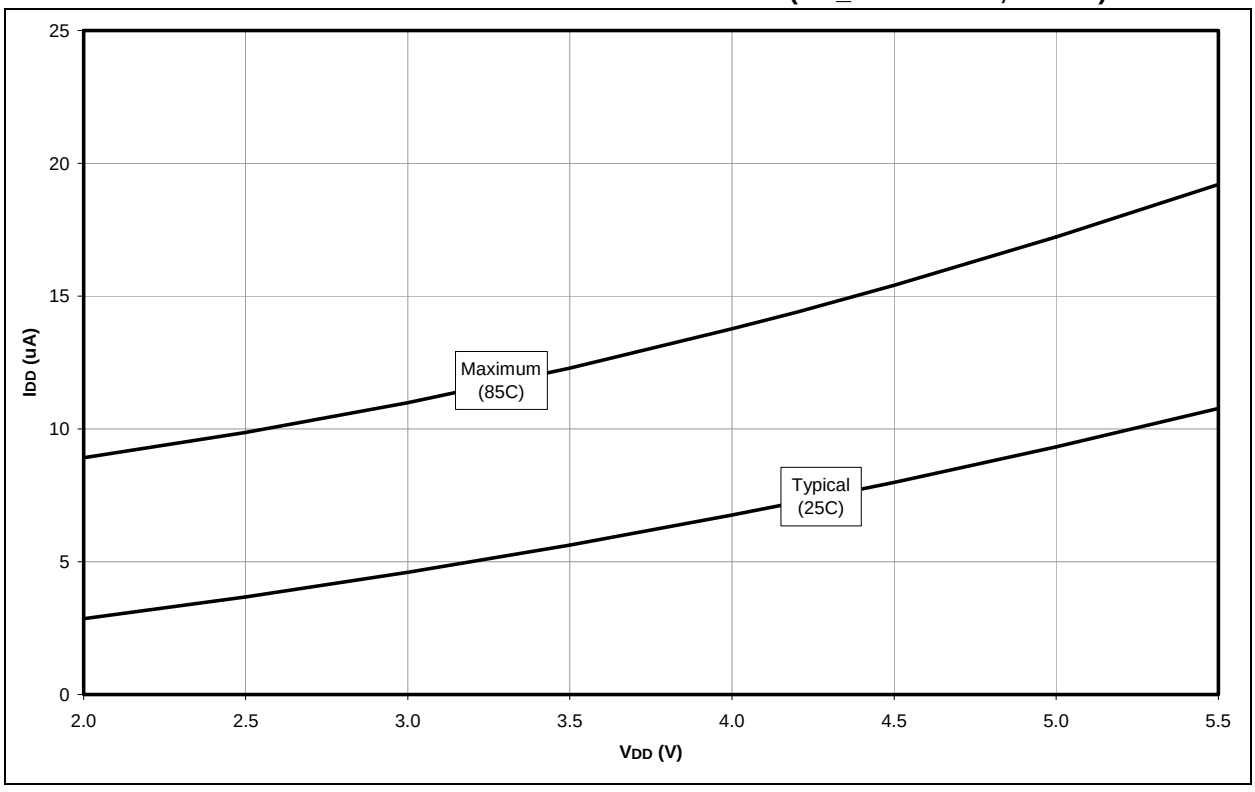
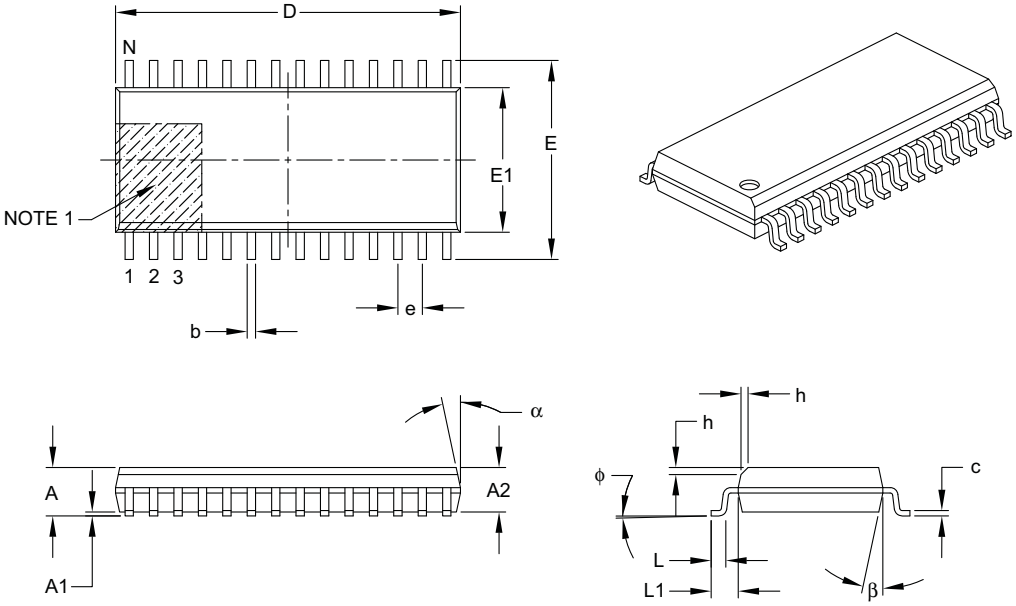


FIGURE 27-16: TYPICAL AND MAXIMUM IDD ACROSS VDD (RC_IDLE MODE, 31 kHz)



28-Lead Plastic Small Outline (SO) – Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	–	–	2.65
Molded Package Thickness	A2	2.05	–	–
Standoff §	A1	0.10	–	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (optional)	h	0.25	–	0.75
Foot Length	L	0.40	–	1.27
Footprint	L1		1.40 REF	
Foot Angle Top	ϕ	0°	–	8°
Lead Thickness	c	0.18	–	0.33
Lead Width	b	0.31	–	0.51
Mold Draft Angle Top	α	5°	–	15°
Mold Draft Angle Bottom	β	5°	–	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-052B